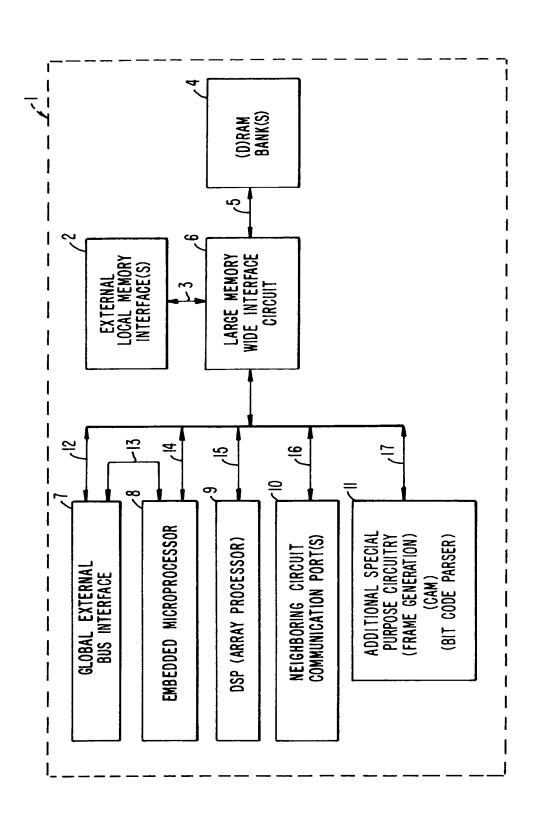
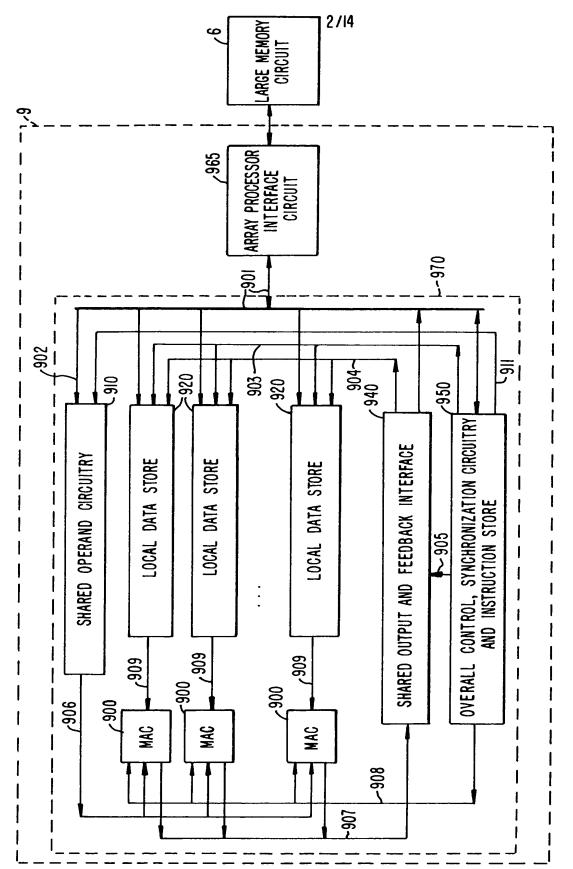




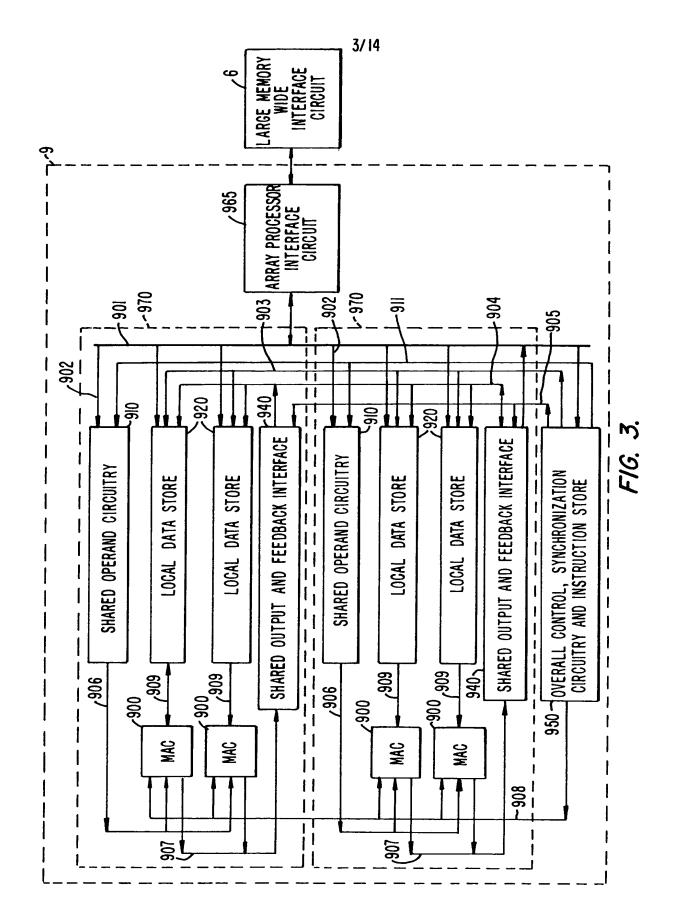


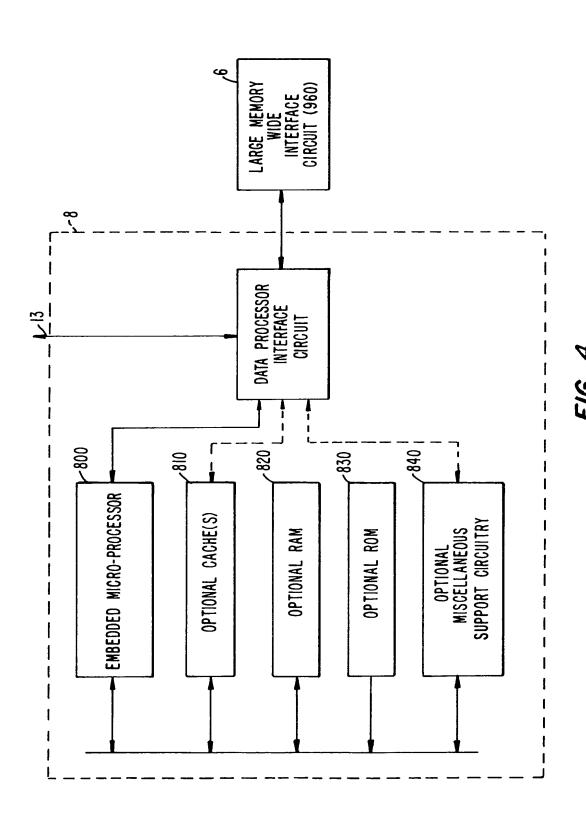
1/14



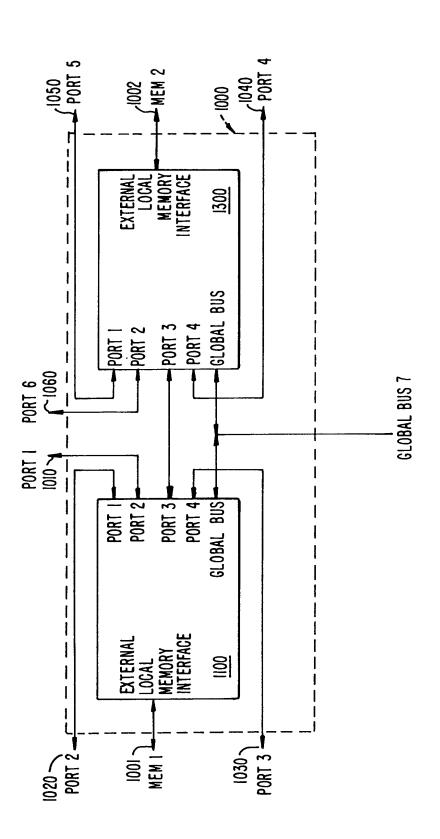


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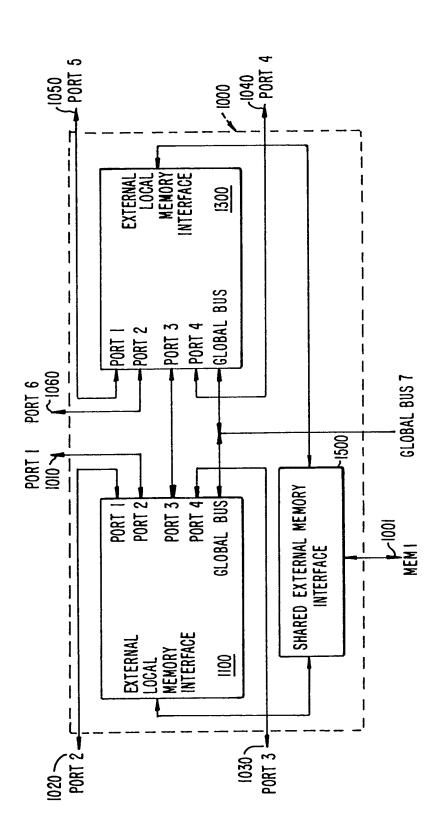




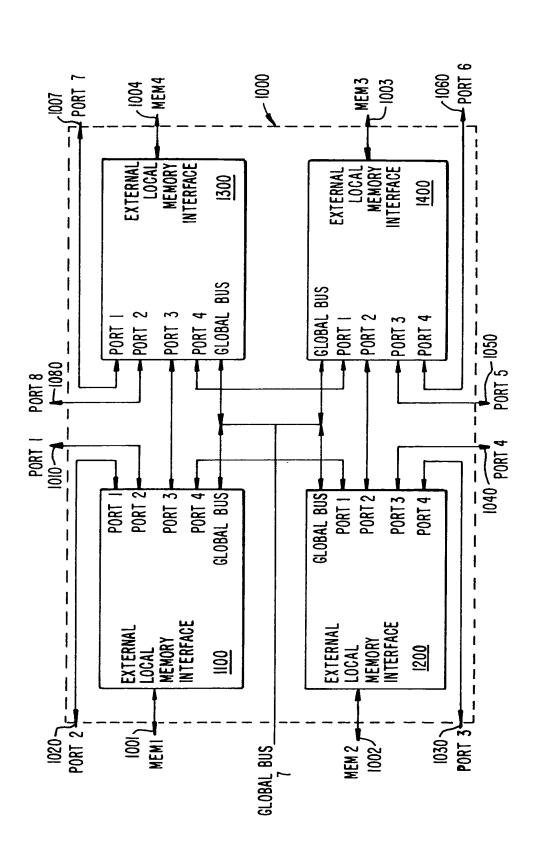
5/14



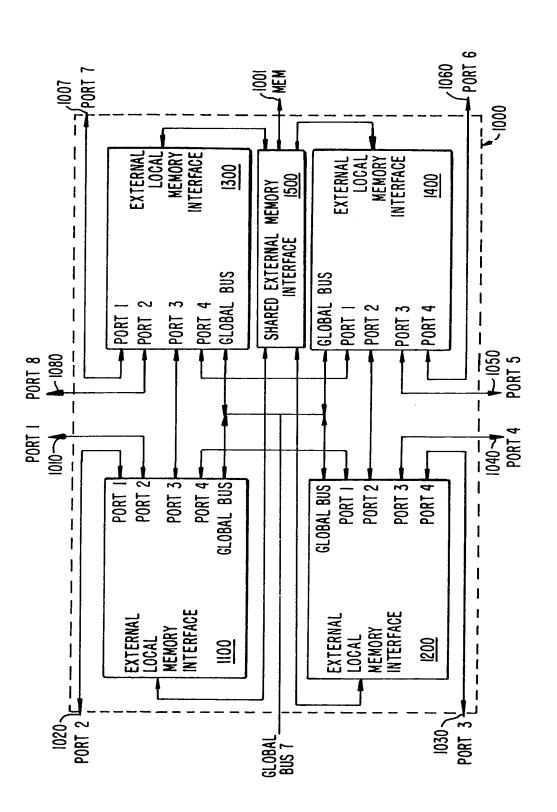
F/G. 5.



F/G. 6.

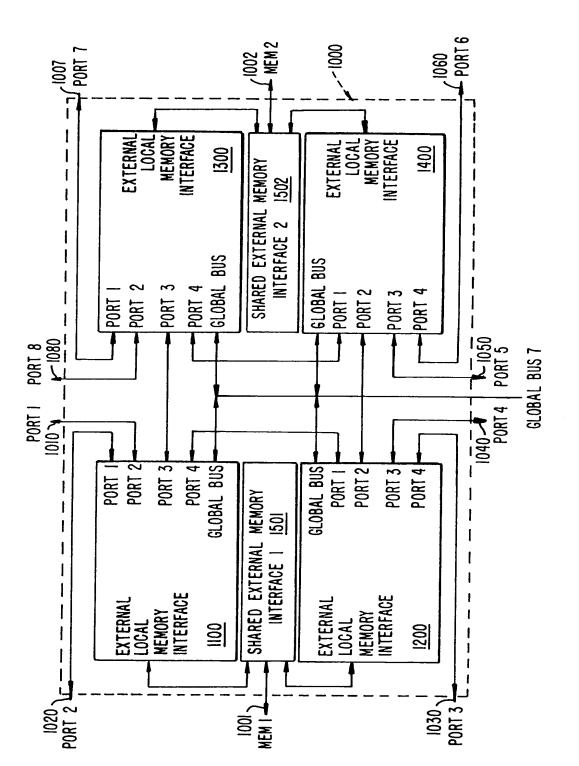


F1G. 7.



F16. 8.

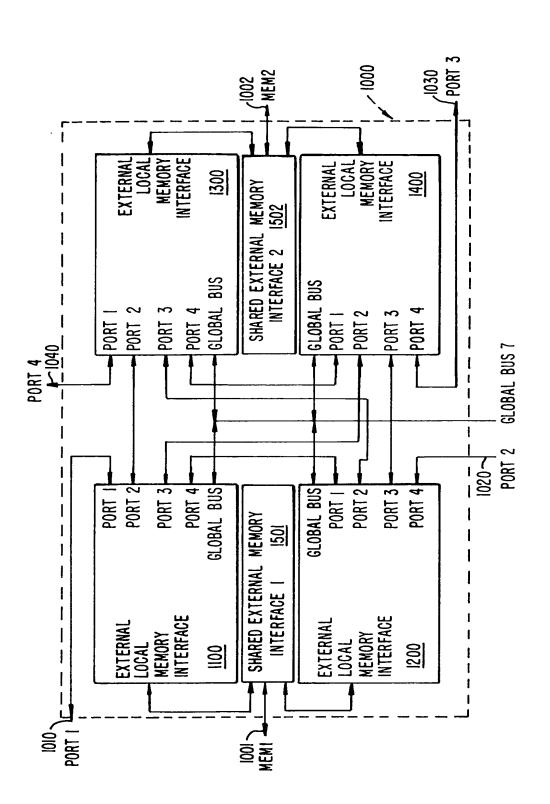
Sheet 9 of 14



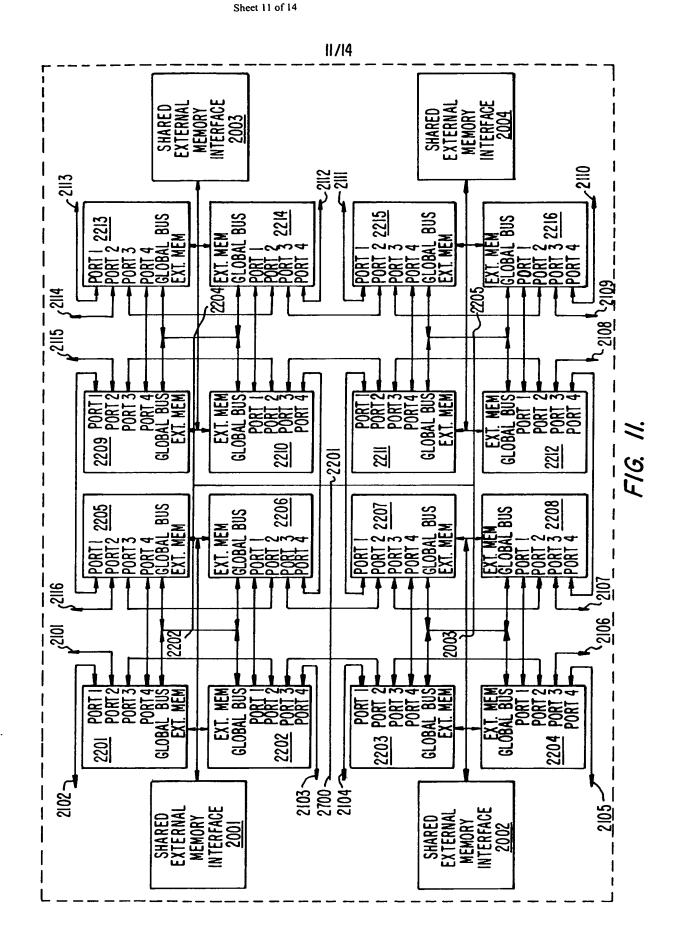
ο, F16.

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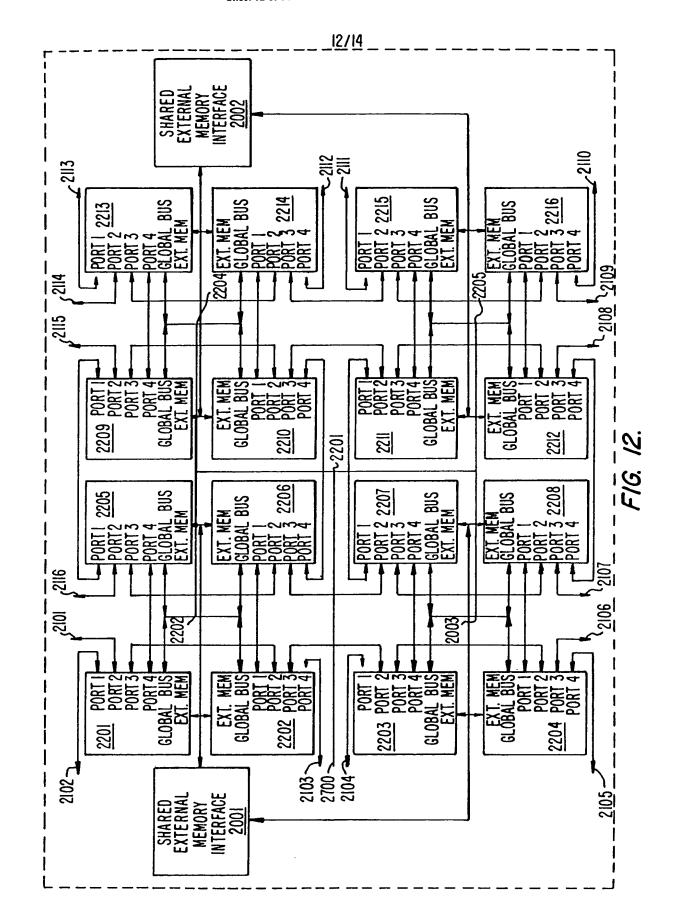
10/14



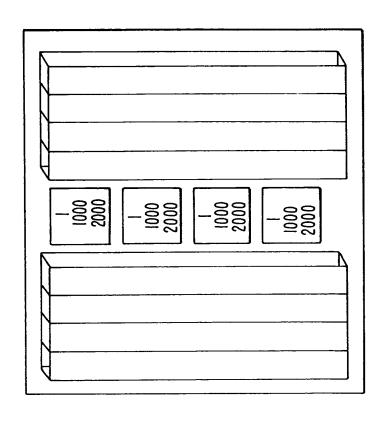
F1G. 10.



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MODULES (168 PIN) WITH UP TO

IGM BY 72 BITS EACH

(8) SYNCHRONOUS DRAM

- (4) EMBODIMENTS

BOARD CONTAINS:

EACH SIDE OF PRINTED CIRCUIT

OVERALL PCB FOOT PRINT:

125MM + 125MM

F16. 13.

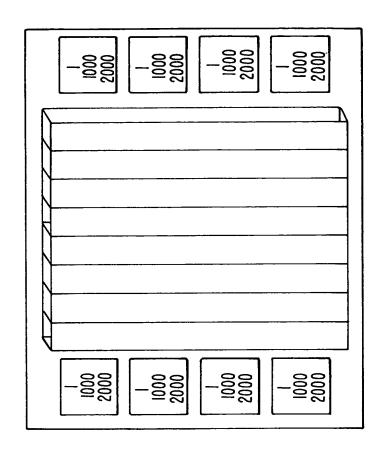
MBYTES OF RAM

— BOOT ROM AND OTHER SUPPORT
CIRCUITRY IS NOT DIAGRAMMED

EACH EMBODIMENT HAS 288

HEDE

14/14



MODULES (168 PIN) WITH UP TO

IGM BY 72 BITS EACH

(8) SYNCHRONOUS DRAM

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- (8) EMBODIMENTS

EACH SIDE OF PRINTED CIRCUIT

BOARD CONTAINS:

OVERALL PCB FOOT PRINT:

125MM * 150MM

EACH EMBODIMENT HAS 144

I

MBYTES OF RAM

F1G. 14.

BOOT ROM AND OTHER SUPPORT CIRCUITRY IS NOT DIAGRAMMED HERE I